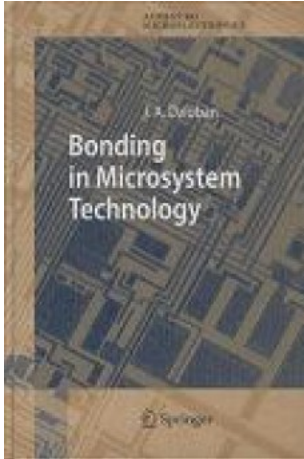


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Sinopsis

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Bonding in Microsystem Technology concerns the exciting field of microsystems (known under varying names as: MEMS, μ TAS (analytical or chemical Microsystems), MOEMS: the micro-miniature devices, utilizing extremely miniaturized mechanical structures made usually from silicon by wet deep anisotropic etching. Such structures cannot be used directly, they must be designed and fabricated as a part of the three dimensional multi-layer sandwich built from silicon or silicon and glass. The procedures of formation of such a sandwich are known as bonding. The book contains the description of wet anisotropic micromachining of basic silicon micromechanical constructions and their utilization in microsystems followed by the detailed discussion of all of methods of bonding used for the formation of silicon and silicon-glass microsystems, with the special attention paid to the anodic bonding technique.